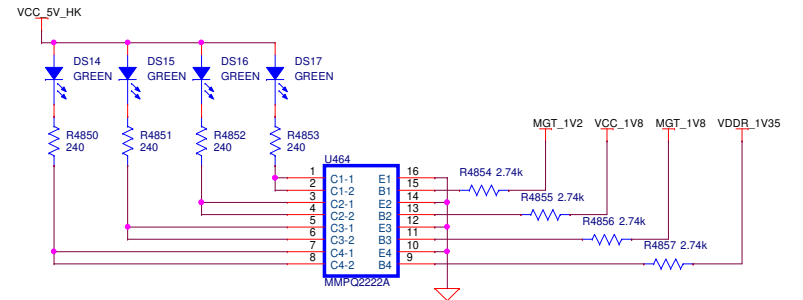
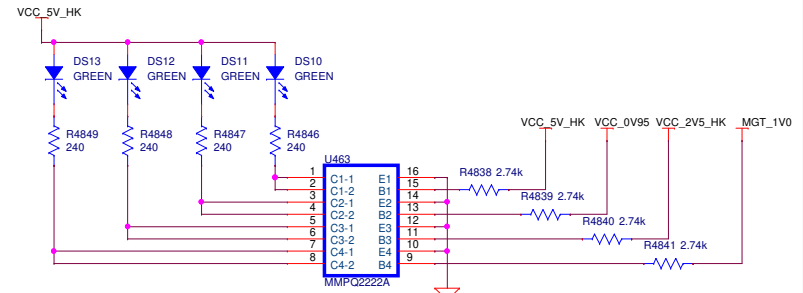
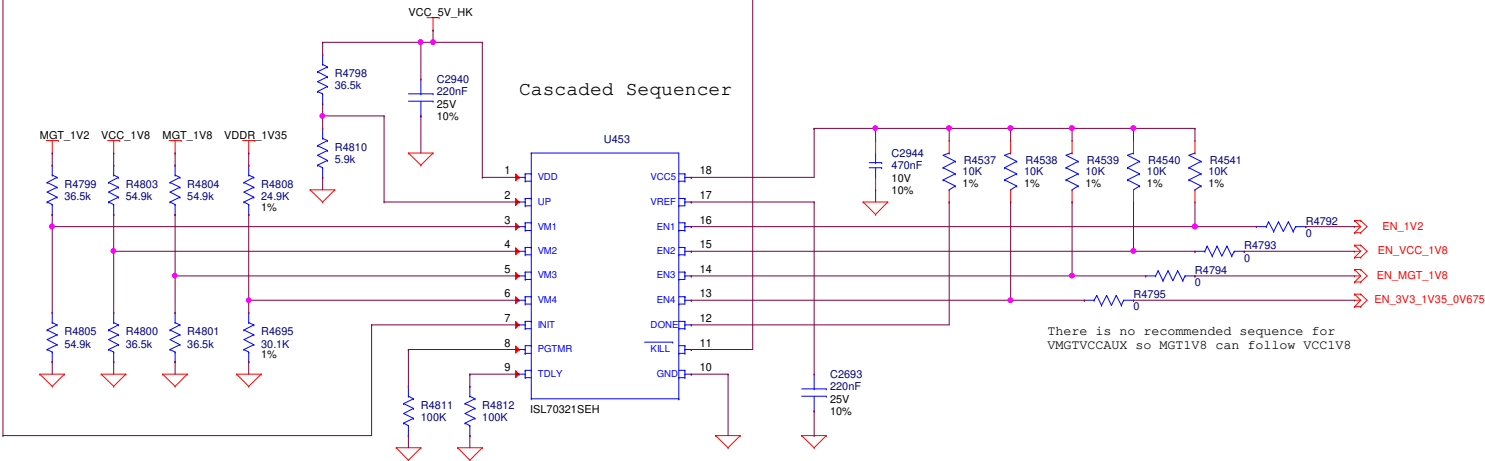
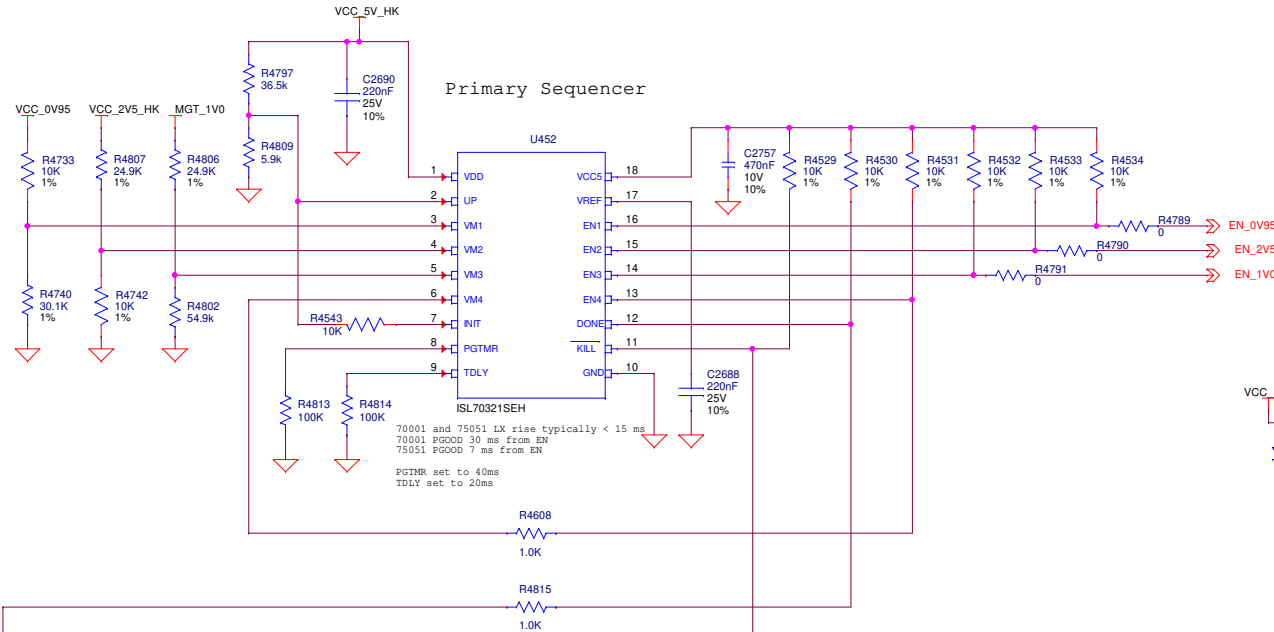


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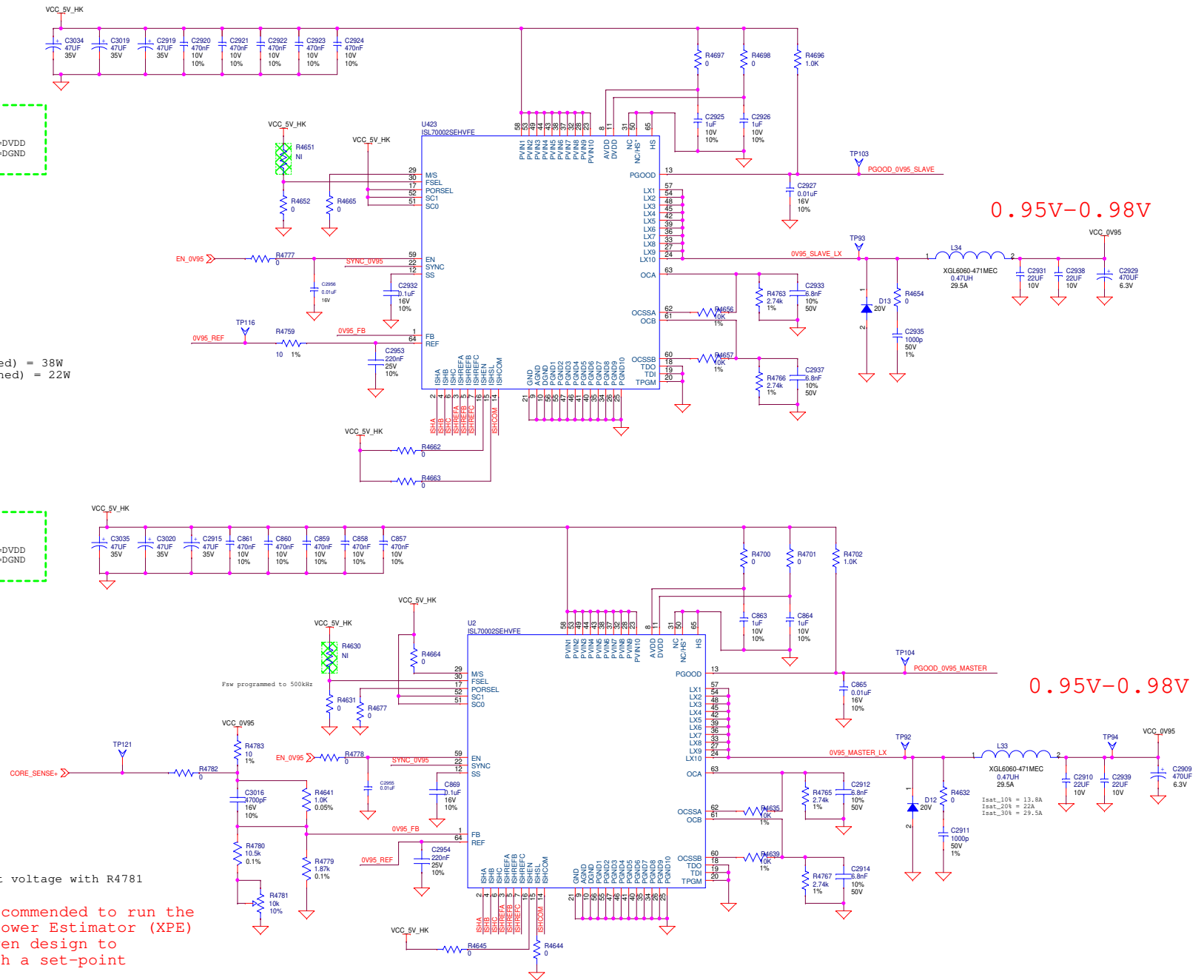
```
Current Share Config
Master: ISHSL = DGND, ISHEN=DVDD, M/S=DVDD
Slave: ISHSL = DVDD, ISHEN=DVDD, M/S=DGND
```

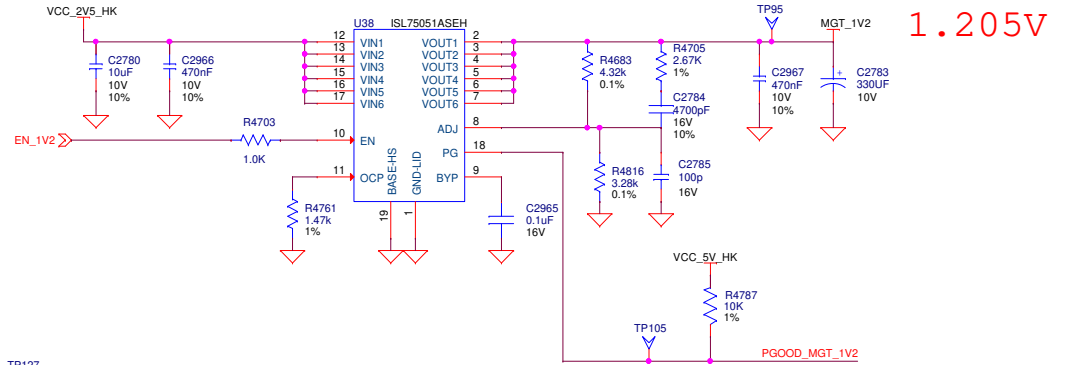
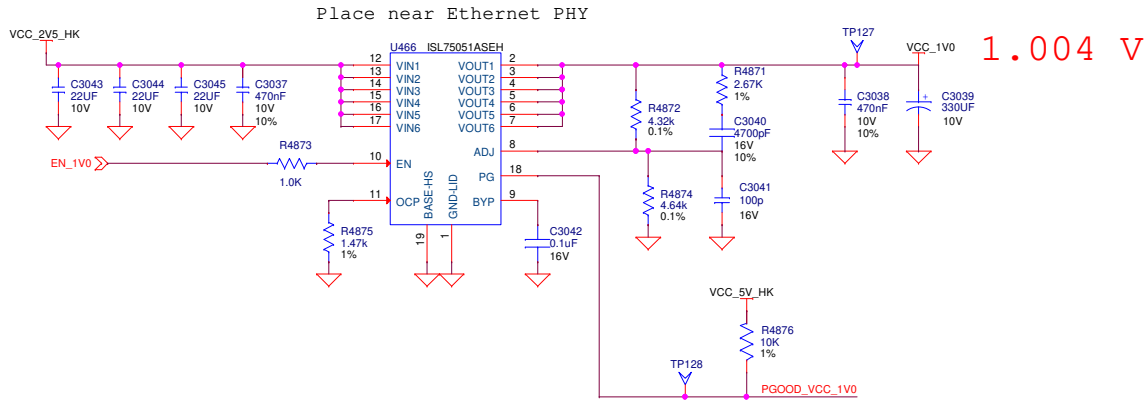
```
Max combined current = 38A
Max current/device = 22A
Efficiency @ 22A = 63%
Maximum power delivered (combined) = 38W
Maximum power dissipated (combined) = 22W
OCP set to 21.9A
SS ramp time = 2.6 ms
```

```
Current Share Config
Master: ISHSL = DGND, ISHEN=DVDD, M/S=DVDD
Slave: ISHSL = DVDD, ISHEN=DVDD, M/S=DGND
```

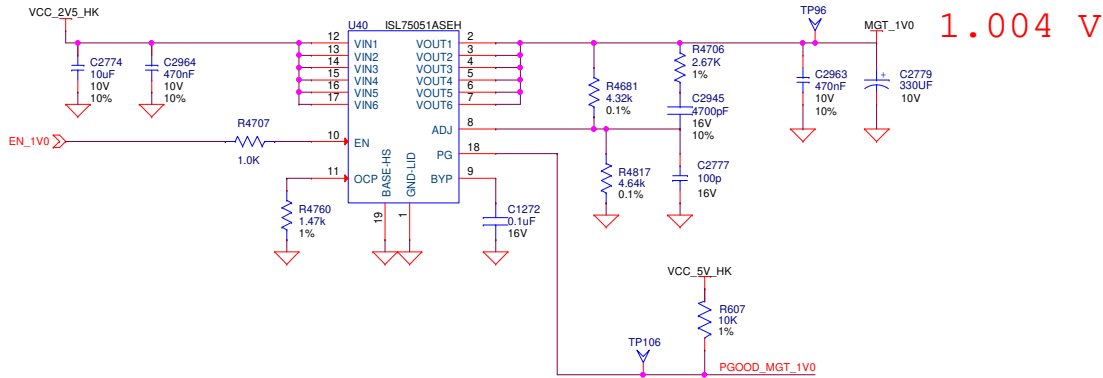
Vary output voltage with R4781

It is recommended to run the Xilinx Power Estimator (XPE) on a given design to establish a set-point





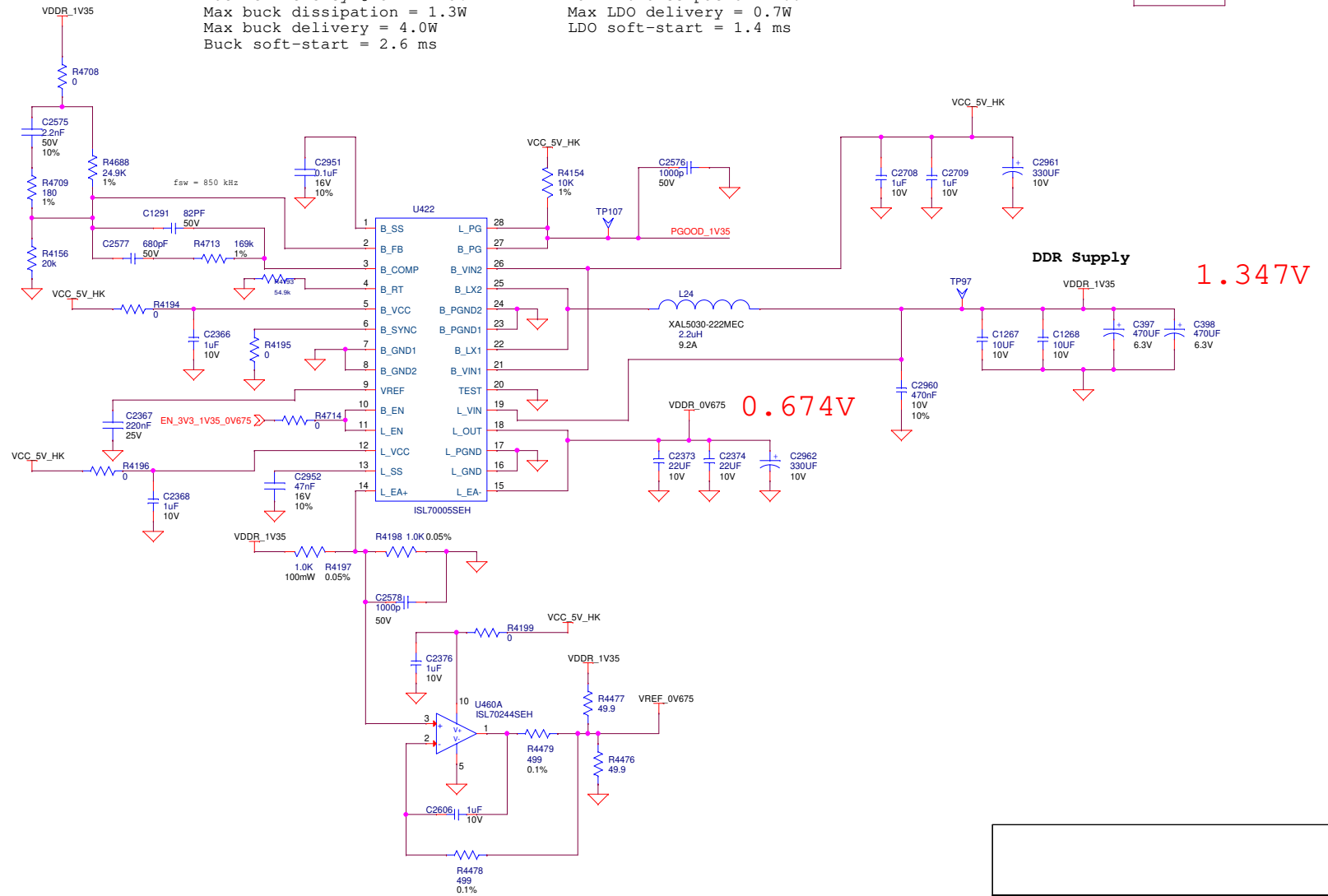
Max current / device = 3A
 OCP set just shy of 3A
 1.2V Max Dissipation = 3.9W
 1.2V Max Delivery = 3.6W
 1.0V Max Dissipation = 4.5W
 1.0V Max Delivery = 3.0W



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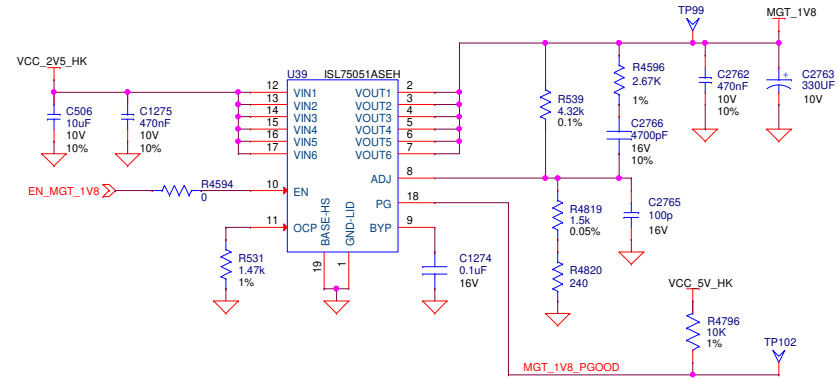
Buck OCP fixed, ~5.3A
 Max buck current = 3A
 Buck efficiency @ 3A = ~75%
 Max buck dissipation = 1.3W
 Max buck delivery = 4.0W
 Buck soft-start = 2.6 ms

LDO OCP fixed, ~1.65A
 Max LDO current = 1A
 Max LDO dissipation = 0.7W
 Max LDO delivery = 0.7W
 LDO soft-start = 1.4 ms



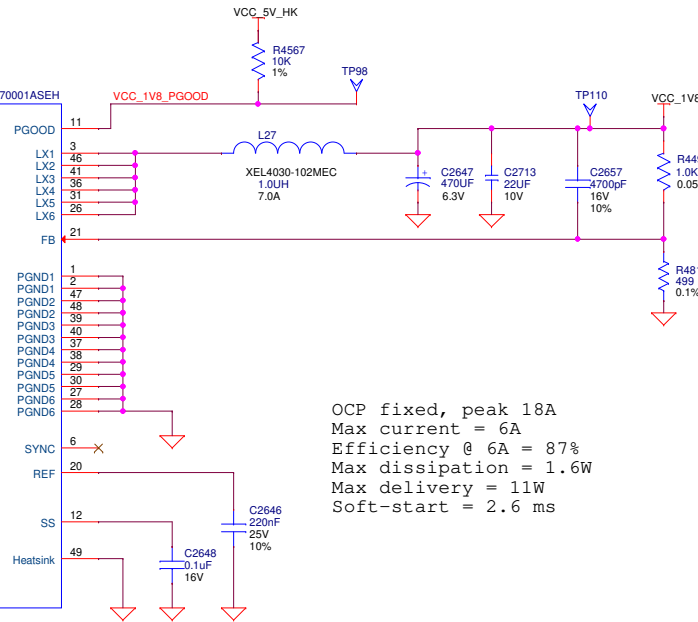
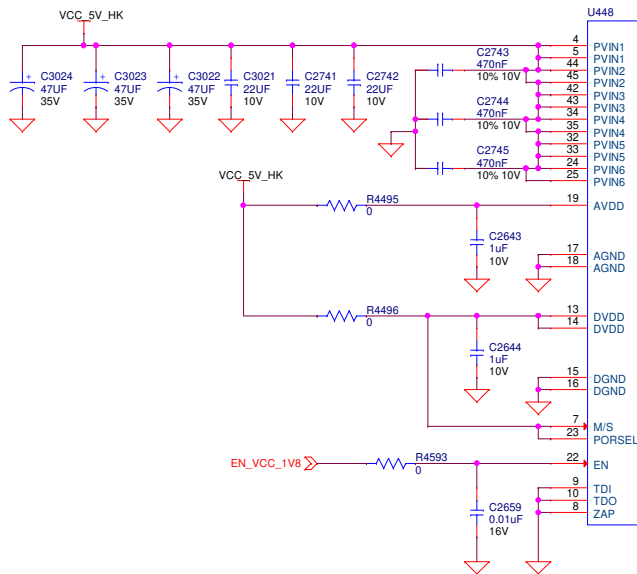
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Max LDO current = 3A
 Max LDO dissipation = 2.1W
 Max LDO delivery = 5.4W
 OCP set just shy of 3A



1.811V

Place 0.47uF, 22uF on the 3 sides of part near PVIN



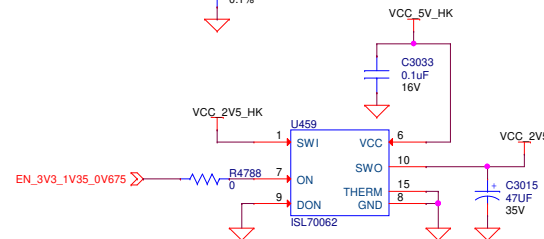
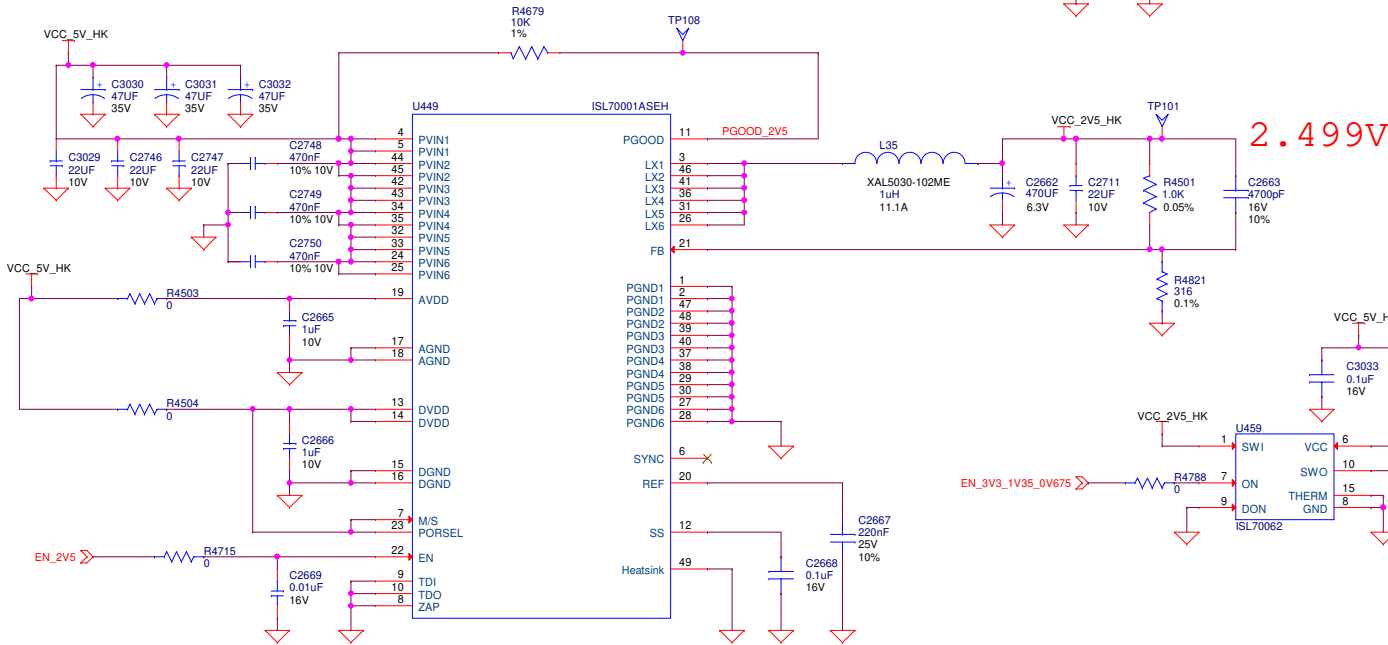
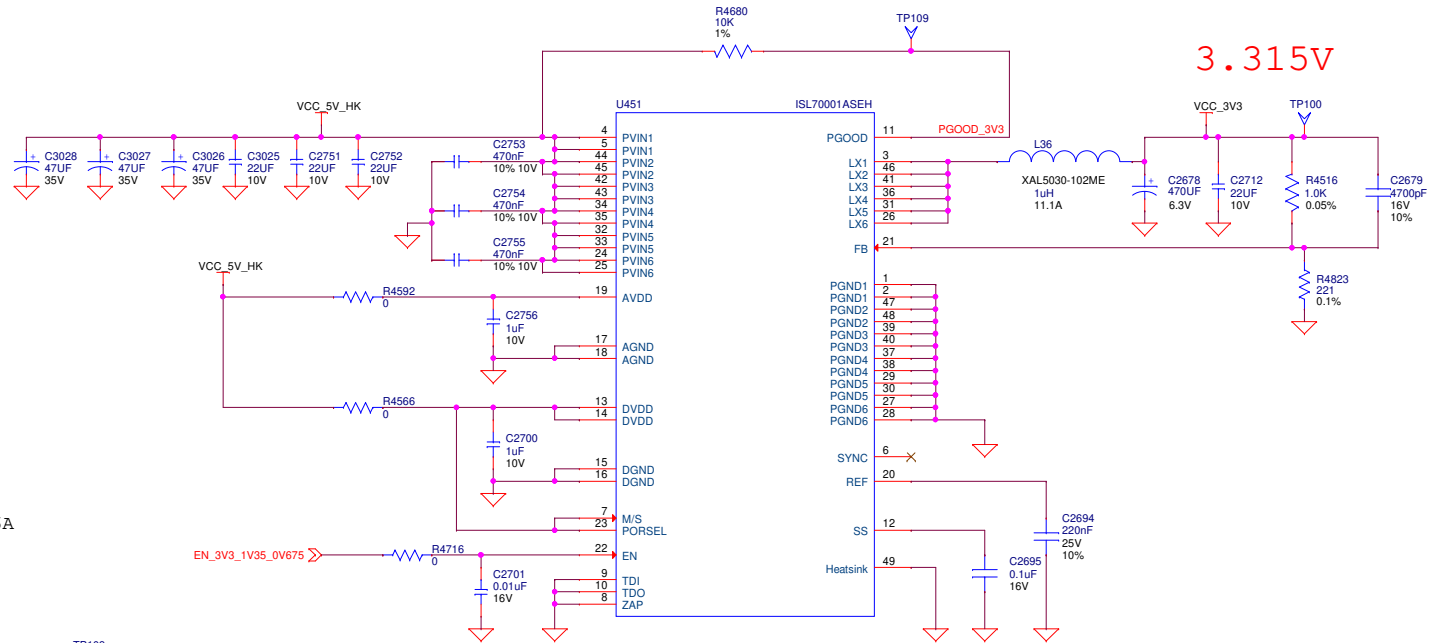
1.802V

OCP fixed, peak 18A
 Max current = 6A
 Efficiency @ 6A = 87%
 Max dissipation = 1.6W
 Max delivery = 11W
 Soft-start = 2.6 ms

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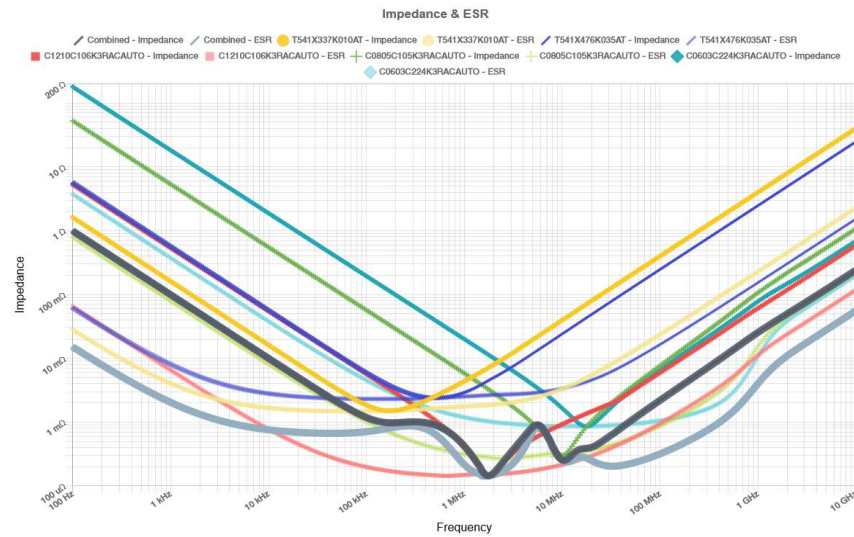
OCP fixed, peak 18A
 Max current = 6A
 Efficiency @ 6A = 87%
 Max dissipation = 3W
 Max delivery = 20W
 Soft-start = 2.6 ms

OCP fixed, peak 18A
 Max continuous current = 6A
 Efficiency @ 6A = 87%
 Max dissipation = 2.3W
 Max delivery = 15.3W
 Soft-start = 2.6 ms

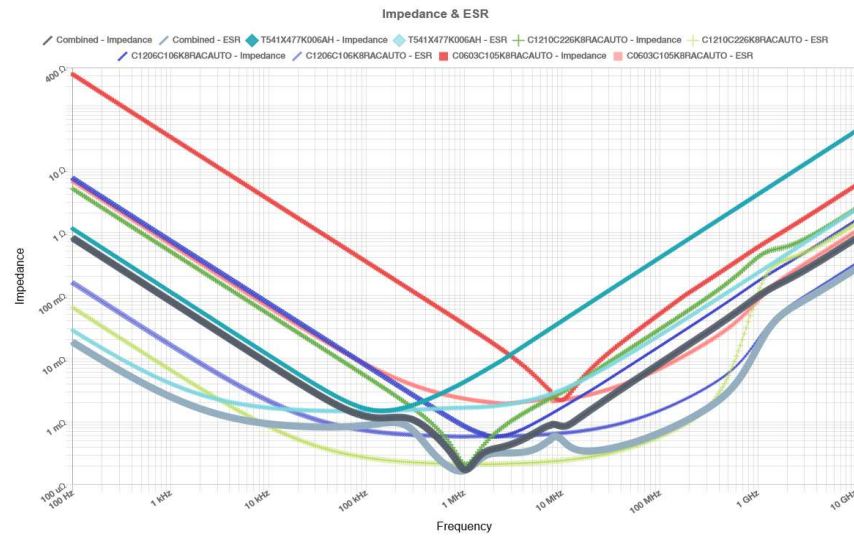


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Xilinx Reference Decoupling Network Impedance:



BOM-Optimized Decoupling Network Impedance:



Decoupling designed to a 6A load step

Recommended PCB Capacitors per Device

Example decoupling capacitor quantities for the XQRKU060-CNA1509 device are listed in Table 77 to Table 81. The optimized quantities of PCB decoupling capacitors assume that the voltage regulators have stable output voltages and meet the regulator manufacturer's minimum output capacitance requirements. These recommendations assume a regulator (DC) tolerance of $\pm 2\%$ and an AC tolerance of $\pm 1\%$, except for V_{CCINT} which assumes an AC tolerance of $\pm 2\%$. The total of the DC and AC tolerances must be within the recommended operating conditions specified in Table 9.

Table 77: Decoupling Capacitor Quantities for V_{CCINT} with Sample Step Currents

Step current (A)	330 μ F	47 μ F	10 μ F	1.0 μ F	0.22 μ F
6	3	30	6	30	40
5	2	5	19	21	25
4	1	4	16	16	16
3	1	2	8	8	8
2	1	1	3	3	3

Notes:

- V_{CCINT_IO} is tied internally in the CNA1509 package to V_{CCINT} .
- Step current is typically a fraction of dynamic current; roughly 15–33%.

Table 78: Decoupling Capacitor Quantities for V_{CCBRAM}

V_{CCBRAM}	
47 μ F	10 μ F
1	1

Table 79: Decoupling Capacitor Quantities for V_{CCAUX}/V_{CCAUX_IO}

V_{CCAUX}/V_{CCAUX_IO} (combined)	
47 μ F	10 μ F
1	1

Notes:

- Based on 2.0A of $I_{CCAUX} + I_{CCAUX_IO}$ dynamic current.

Table 80: Decoupling Capacitor Quantities for V_{CCO} per Bank

V_{CCO_HP} (per bank) or V_{CCO_HR} (per bank)	
47 μ F	10 μ F
1	1

Notes:

- When combining banks, one 47 μ F can power up to four connected banks.

Table 81: Decoupling Capacitor Specifications and Sample Part Numbers

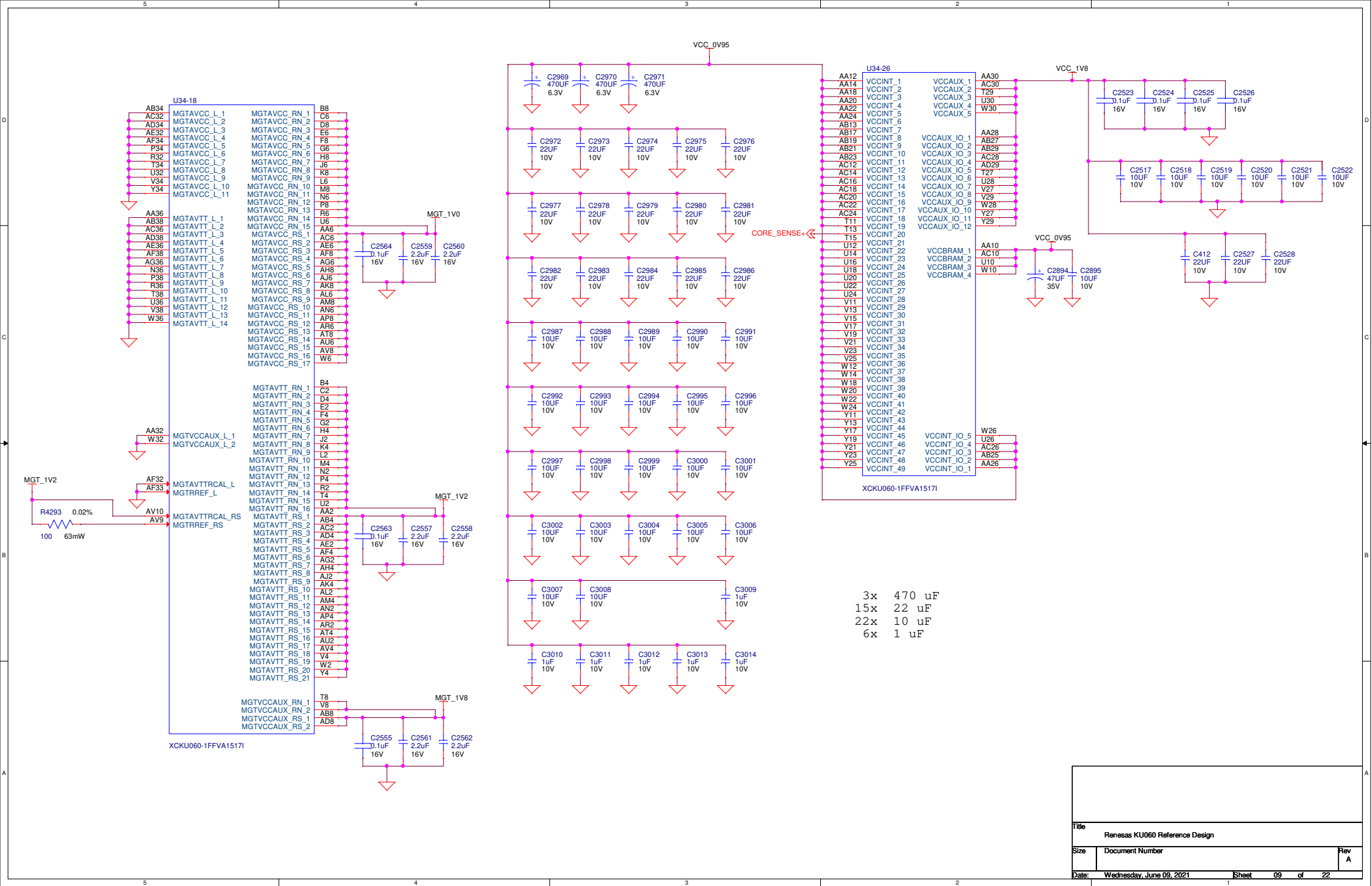
Value (μ F)	Case	Type	ESR (m Ω)	ESL (nH)	Sample Part Number
330	D	Tant Poly	5.84	1.90	Kemet T541X337K010AT
47	D	Tant Poly	15.22	1.90	Kemet T541D476K3.SATE
10	1210	X7R	20	1.62	
1.0	0805	X7R	19	2.50	
0.22	0603	X7R	12	2.50	

Decoupling methods other than those presented in these tables can be used, but the decoupling network should be designed to meet or exceed the performance of the simple decoupling networks presented here. The impedance of the alternate network is recommended to be less than or equal to that of the recommended network across frequencies from 100 kHz to approximately 10 MHz.

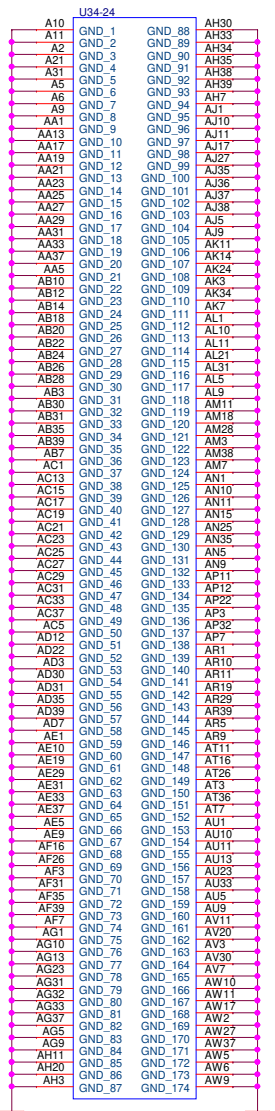
Using KEMET's K-SIM capacitor simulation software we find that the Xilinx design has peak impedance of about 1.5 m Ω over frequency. Iterating in the same tool we derive a network with a similar figure, but fewer components. This reduces the BOM and simplifies PCB layout.

Both designs are under $Z_{target} = 3\text{m}\Omega$.

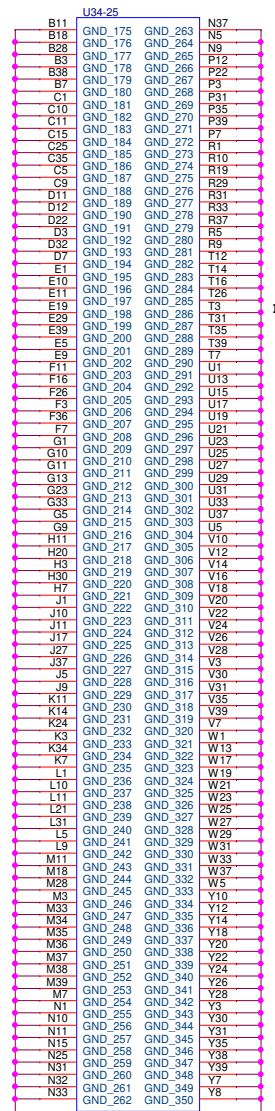
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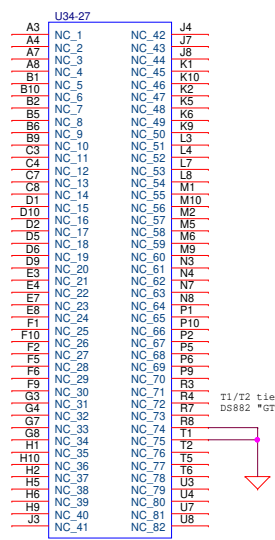
A2 is NC on A1517 (CGA) Pinout



AW2 is NC on A1517 (CGA) Pinout

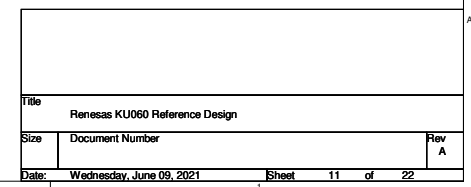


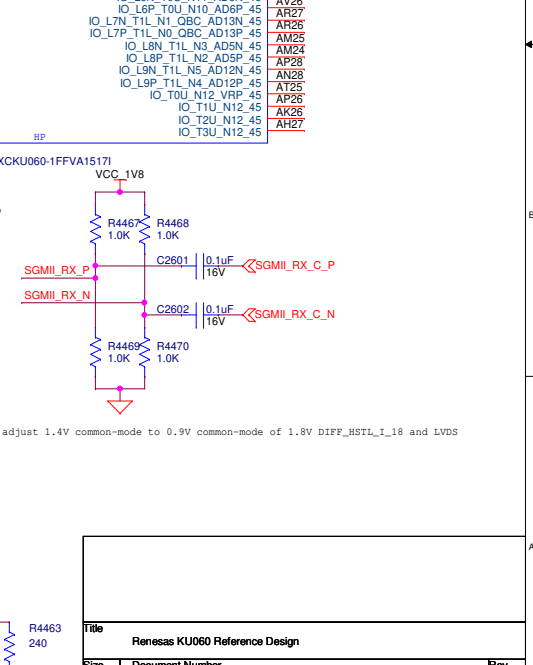
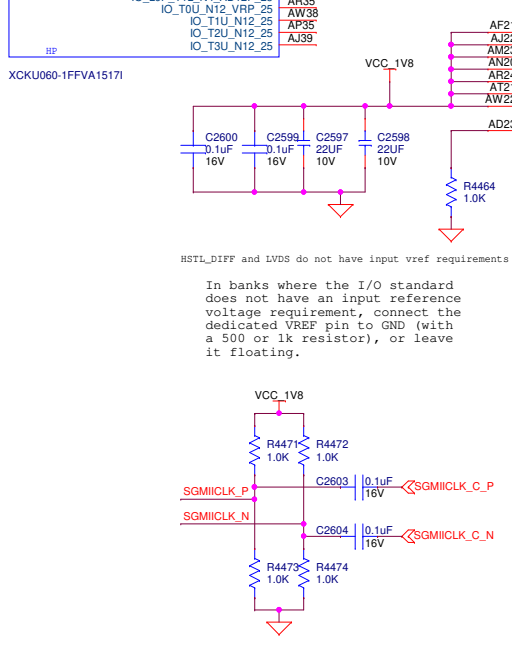
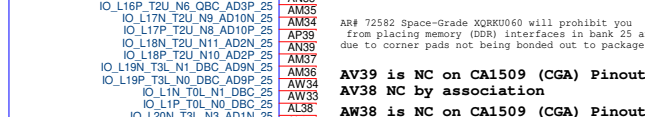
B1 is NC on A1517 (CGA) Pinout



Bank 224 corner transceiver moved to pins T1,T2 on XQRK060 Package

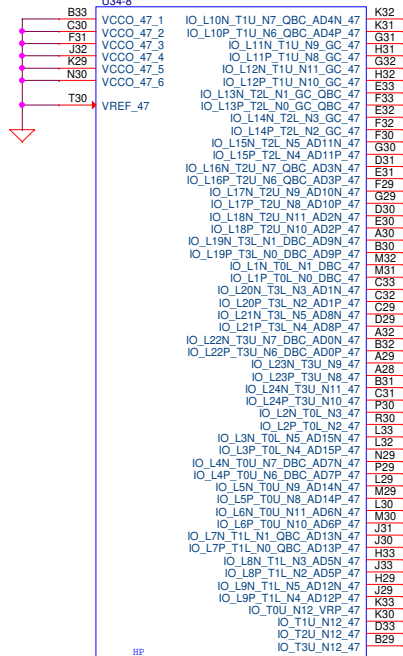
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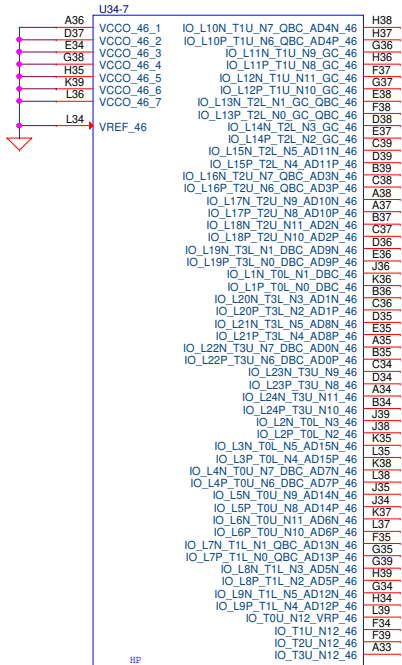
HP Voltage = 0.950 V to 1.890 V
Maximum clamp-current per pin = 10mA
Maximum clamp-current per 52-pin bank = 200mA



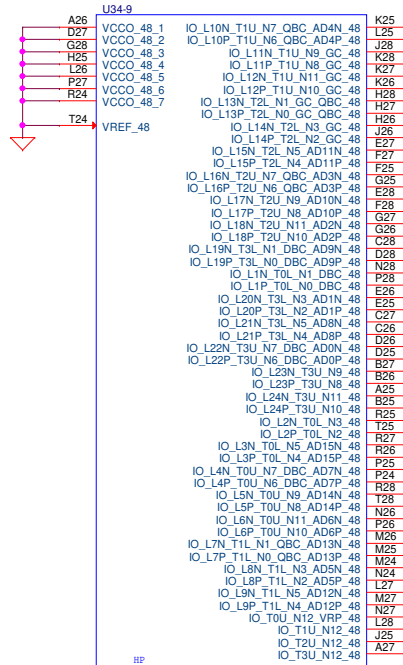
XCKU060-1FFVA15171

B39 is NC on CA1509 (CGA) Pinout
C38 NC by association
A38 is NC on A1509 (CGA) Pinout
A37 NC by association

AR# 72582 Space-Grade XQRKU060 will prohibit you
from placing memory (DDR) interfaces in bank 25 and/or bank 46
Due to corner-pads not being bonded out to package



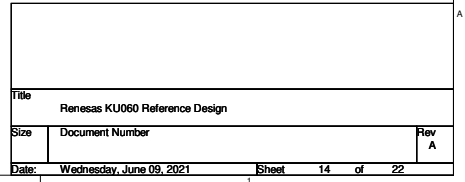
XCKU060-1FFVA15171



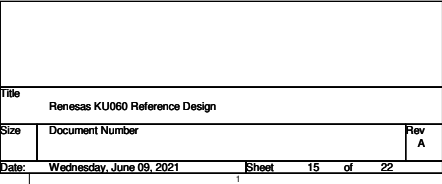
XCKU060-1FFVA15171

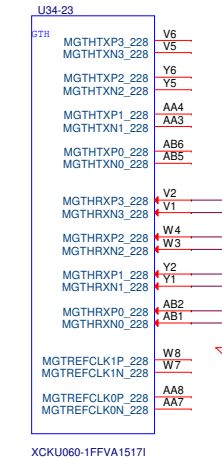
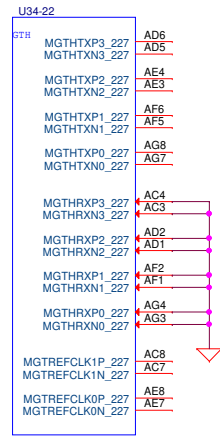
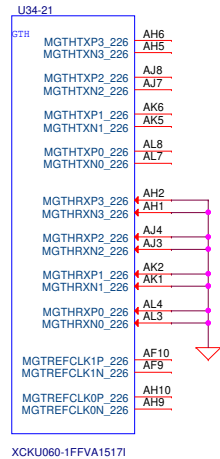
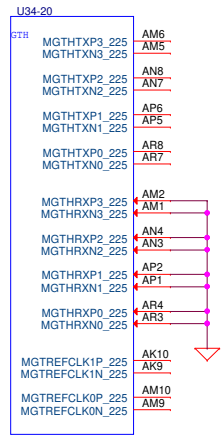
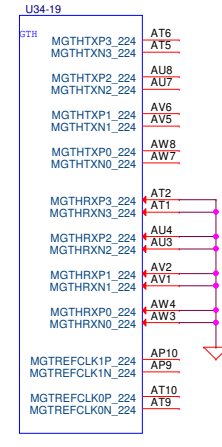
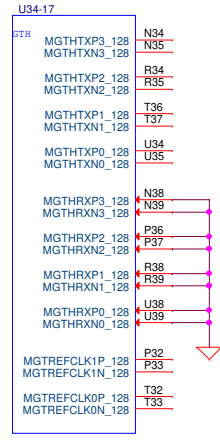
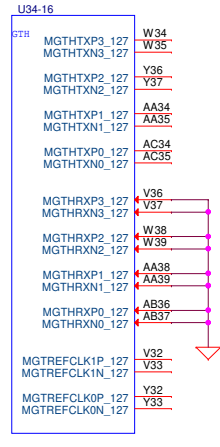
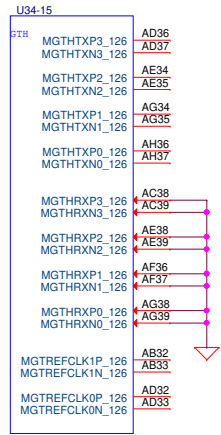
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Max memory interfaces speed is 1600Mb/s according to table 26 in DS892 (-1L speed grade, 0.95V core, FF package)

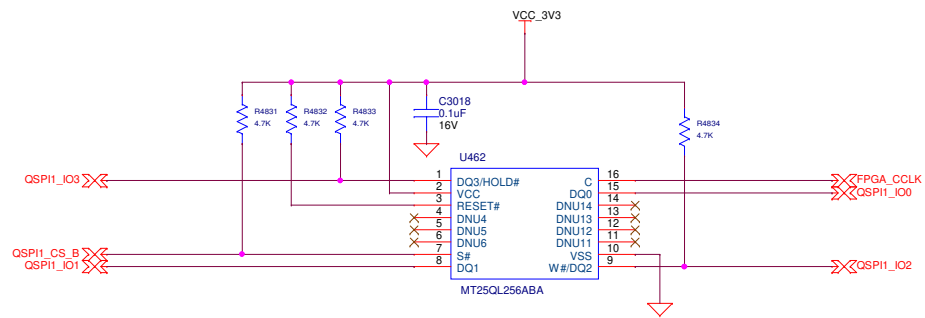
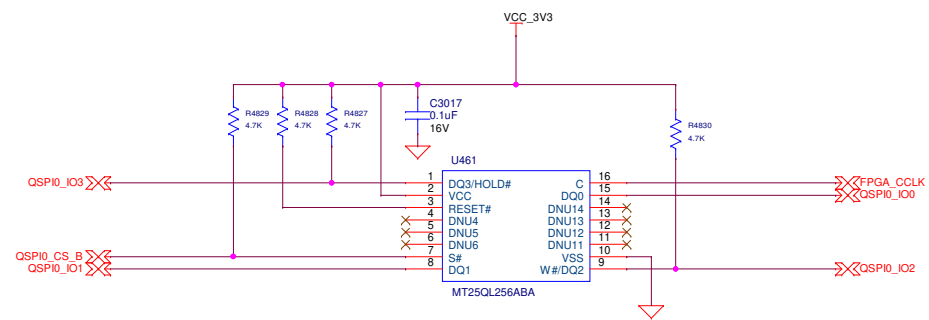


In devices where bank 65 (all devices) and bank 70 (only devices with multiple SLRs) are HR I/O banks and configured with a VCCO requirement $\leq 1.8V$, the inputs can have 0-1-0 transition to the interconnect logic during configuration if the input is tied to a 0 or floated and the configuration voltage is $\geq 2.5V$.

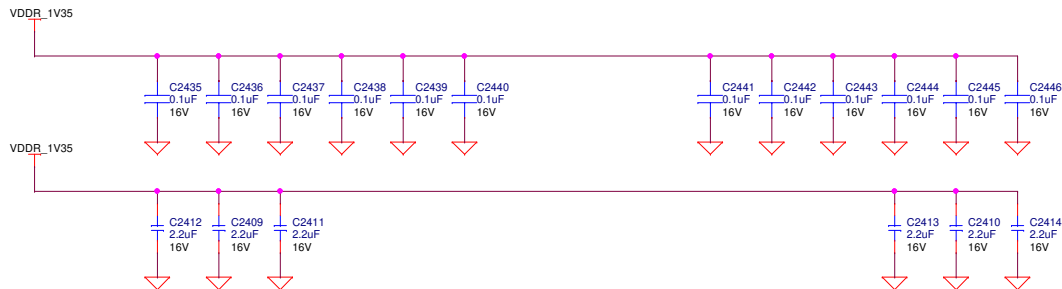
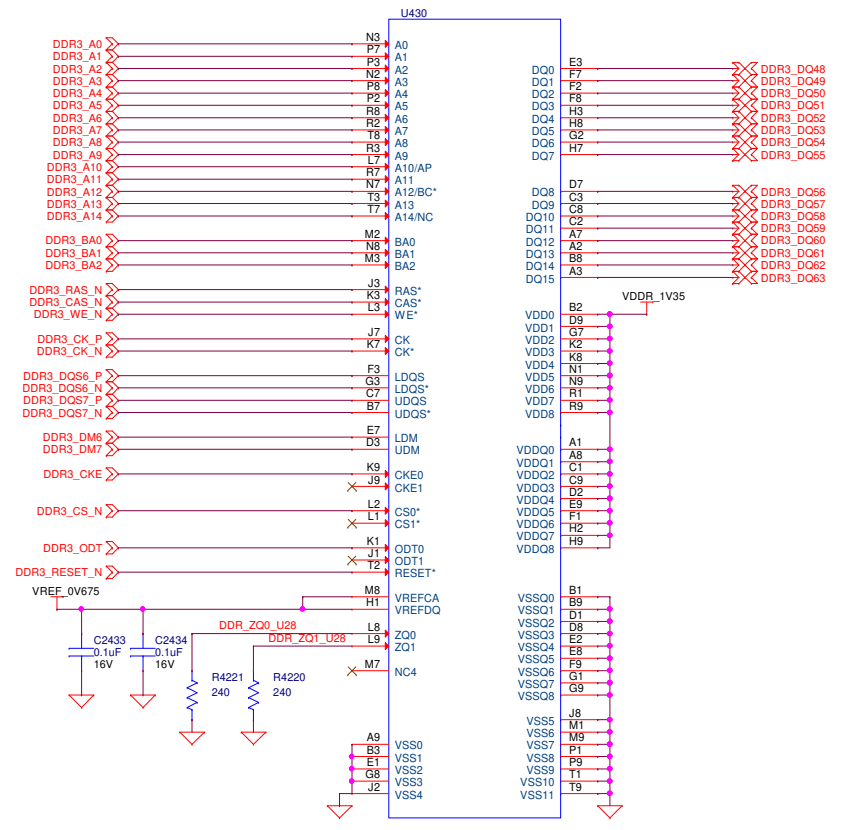
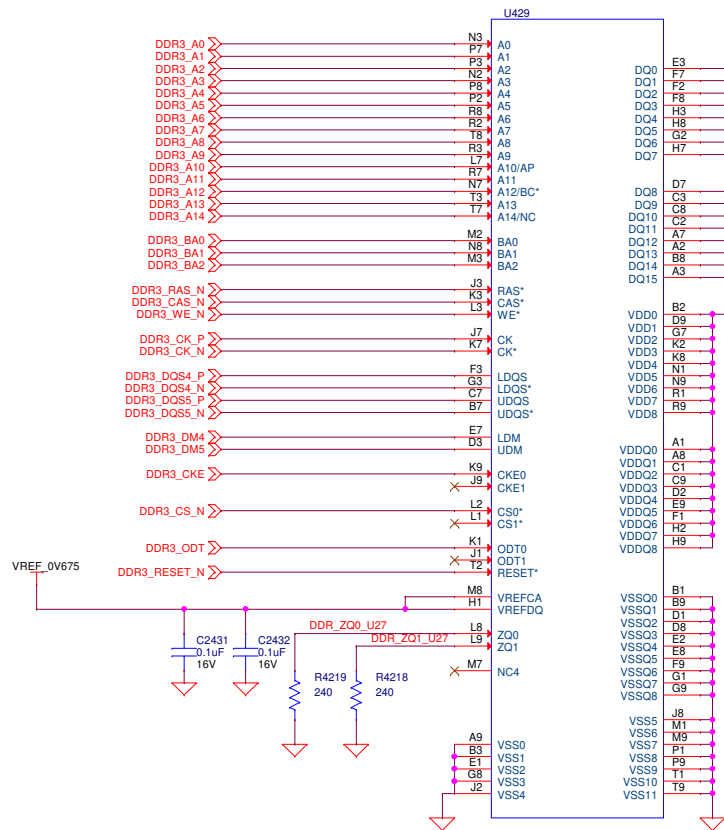




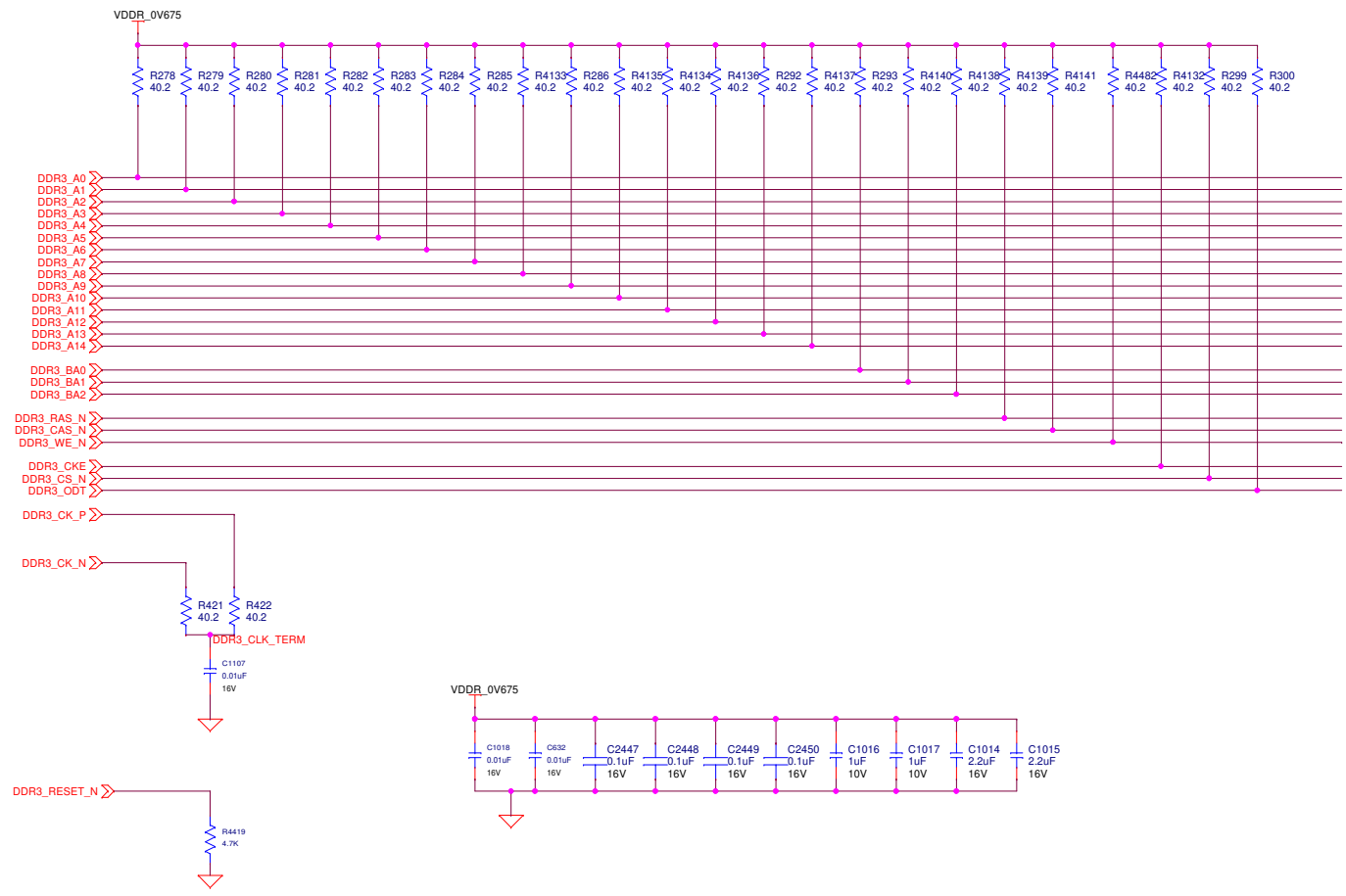
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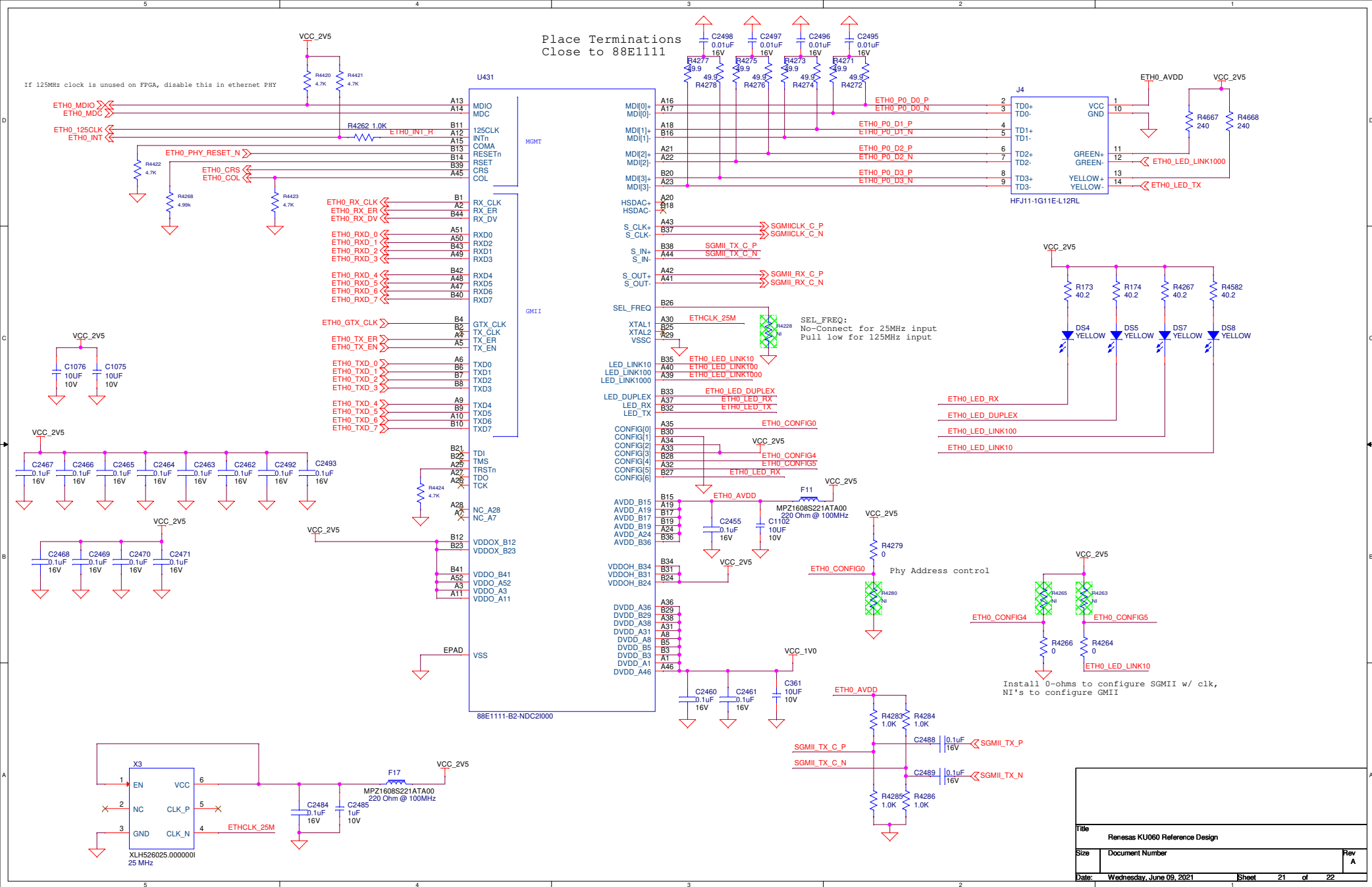
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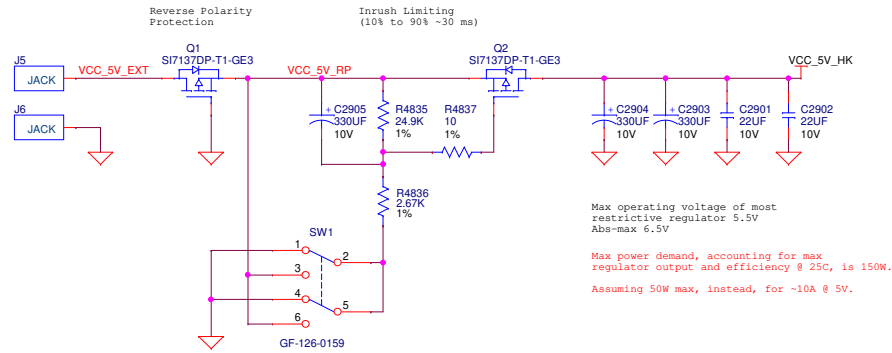
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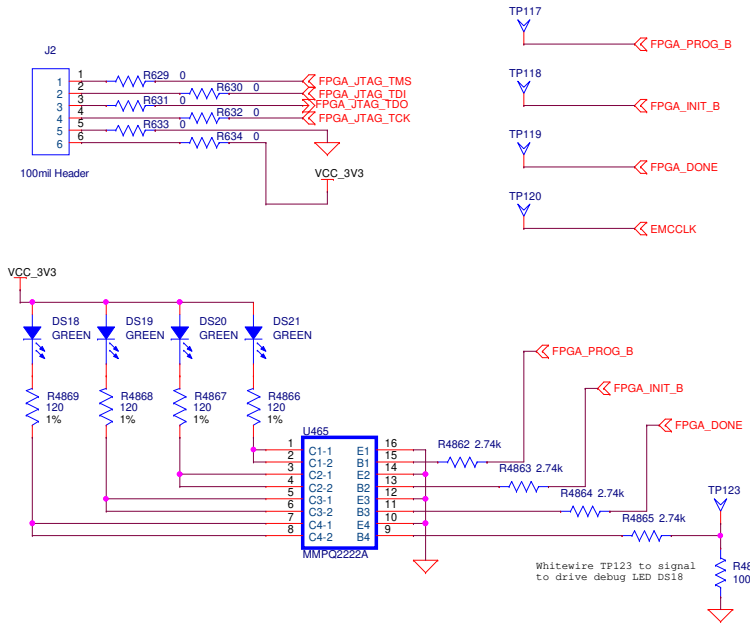
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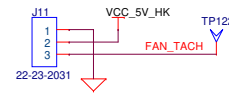
5V Power Input



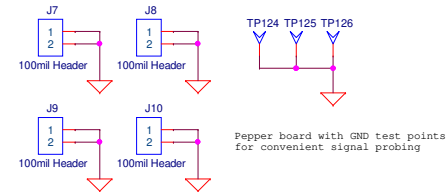
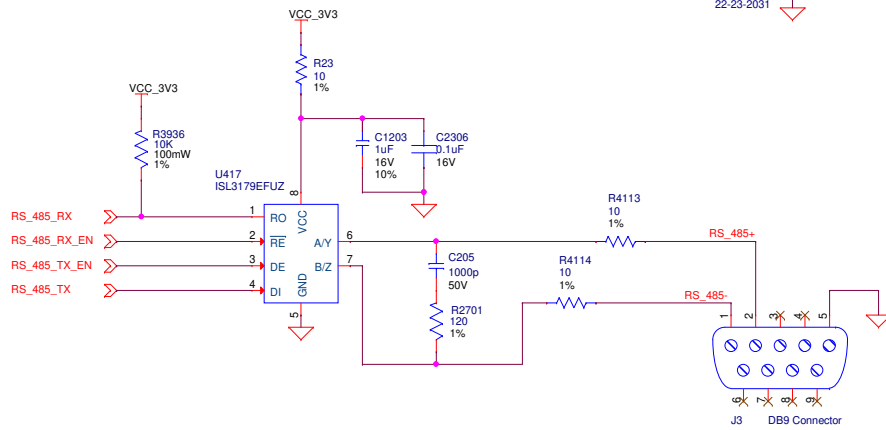
JTAG and FPGA Configuration



FPGA Fan



RS-485



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